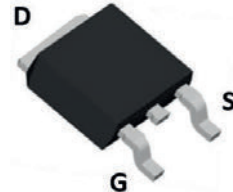
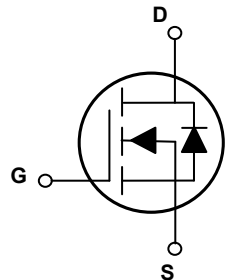


### Main Product Characteristics

|               |             |
|---------------|-------------|
| $V_{(BR)DSS}$ | 150V        |
| $R_{DS(ON)}$  | 14mΩ (Max.) |
| $I_D$         | 100A        |



TO-252 (DPAK)



Schematic Diagram



### Features and Benefits

- Grand Turbo MOSFET process technology.
- Optimized the cell structure.
- Low on-resistance with low gate charge.
- Featuring low switching and drive losses.
- Fast switching and reverse body recovery.
- High ruggedness and robustness.

### Description

The GSFD14015 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

### Absolute Maximum Ratings ( $T_J=25^{\circ}\text{C}$ unless otherwise specified)

| Parameter                                                             | Symbol          | Max.        | Unit                  |
|-----------------------------------------------------------------------|-----------------|-------------|-----------------------|
| Drain-Source Voltage                                                  | $V_{(BR)DSS}$   | 150         | V                     |
| Gate-Source Voltage                                                   | $V_{GS}$        | $\pm 20$    | V                     |
| Drain Current-Continuous ( $T_C=25^{\circ}\text{C}$ ) @ Steady-State  | $I_D$           | 100         | A                     |
| Drain Current-Continuous ( $T_C=100^{\circ}\text{C}$ ) @ Steady-State |                 | 63          |                       |
| Pulsed Drain Current <sup>2</sup>                                     | $I_{DM}$        | 400         | A                     |
| Single Pulse Avalanche Energy <sup>1</sup>                            | $E_{AS}$        | 162         | mJ                    |
| Single Pulsed Avalanche Current                                       | $I_{AS}$        | 57          | A                     |
| Power Dissipation ( $T_C=25^{\circ}\text{C}$ ) <sup>3</sup>           | $P_D$           | 100         | W                     |
|                                                                       |                 | 0.8         | W/ $^{\circ}\text{C}$ |
| Junction-to-Ambient (PCB Mounted, Steady-State)                       | $R_{\theta JA}$ | 50          | $^{\circ}\text{C/W}$  |
| Junction to Case                                                      | $R_{\theta JC}$ | 1.25        | $^{\circ}\text{C/W}$  |
| Operating Junction Temperature Range                                  | $T_J$           | -55 to +150 | $^{\circ}\text{C}$    |
| Storage Temperature Range                                             | $T_{STG}$       | -55 to +150 | $^{\circ}\text{C}$    |
| Soldering Temperature                                                 | $T_{SOLD}$      | 260         | $^{\circ}\text{C}$    |

**Electrical Characteristics** ( $T_J=25^{\circ}\text{C}$  unless otherwise specified)

| Parameter                                              | Symbol               | Conditions                                                                            | Min. | Typ. | Max. | Unit |
|--------------------------------------------------------|----------------------|---------------------------------------------------------------------------------------|------|------|------|------|
| On / Off Characteristics                               |                      |                                                                                       |      |      |      |      |
| Drain-Source Breakdown Voltage                         | BV <sub>DSS</sub>    | V <sub>GS</sub> =0V, I <sub>D</sub> =250uA                                            | 150  | -    | -    | V    |
| Drain-Source Leakage Current                           | I <sub>DSS</sub>     | V <sub>DS</sub> =150V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C                      | -    | -    | 1    | μA   |
|                                                        |                      | V <sub>DS</sub> =150V, V <sub>GS</sub> =0V, T <sub>J</sub> =125°C                     | -    | 5    | -    | μA   |
| Gate-Source Forward Leakage                            | I <sub>GSS</sub>     | V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V                                            | -    | -    | ±100 | nA   |
| Static Drain-Source On-Resistance                      | R <sub>DS(ON)</sub>  | V <sub>GS</sub> =10V, I <sub>D</sub> =50A                                             | -    | 12.5 | 14   | mΩ   |
| Gate Resistance                                        | R <sub>g</sub>       | F=1MHz                                                                                | -    | 1.6  | -    | Ω    |
| Gate Threshold Voltage                                 | V <sub>GS(TH)</sub>  | V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA                              | 2    | -    | 2.4  | V    |
| Dynamic and Switching Characteristics                  |                      |                                                                                       |      |      |      |      |
| Total Gate Charge <sup>4,5</sup>                       | Q <sub>g</sub>       | V <sub>DD</sub> =75V, I <sub>D</sub> =50A, V <sub>GS</sub> =10V                       | -    | 36   | -    | nC   |
| Gate-Source Charge <sup>4,5</sup>                      | Q <sub>gs</sub>      |                                                                                       | -    | 24   | -    |      |
| Gate-to-Drain("Miller") Charge <sup>4,5</sup>          | Q <sub>gd</sub>      |                                                                                       | -    | 4.8  | -    |      |
| Gate Plateau <sup>4,5</sup>                            | V <sub>plateau</sub> |                                                                                       | -    | 8    | -    | V    |
| Turn-On Delay Time <sup>4,5</sup>                      | t <sub>d(on)</sub>   | V <sub>DD</sub> =75V, R <sub>G</sub> =1.6Ω, V <sub>GS</sub> =10V, I <sub>D</sub> =50A | -    | 22   | -    | nS   |
| Rise Time <sup>4,5</sup>                               | t <sub>r</sub>       |                                                                                       | -    | 25   | -    |      |
| Turn-Off Delay Time <sup>4,5</sup>                     | t <sub>d(off)</sub>  |                                                                                       | -    | 25   | -    |      |
| Fall Time <sup>4,5</sup>                               | t <sub>f</sub>       |                                                                                       | -    | 11   | -    |      |
| Input Capacitance                                      | C <sub>iss</sub>     | V <sub>DS</sub> =75V, V <sub>GS</sub> =0V, F=1MHz                                     | -    | 2614 | -    | pF   |
| Output Capacitance                                     | C <sub>oss</sub>     |                                                                                       | -    | 328  | -    |      |
| Reverse Transfer Capacitance                           | C <sub>rss</sub>     |                                                                                       | -    | 15   | -    |      |
| Drain-Source Diode Characteristics and Maximum Ratings |                      |                                                                                       |      |      |      |      |
| Continuous Source Current (Body Diode)                 | I <sub>s</sub>       | MOSFET symbol showing the integral reverse p-n junction diode.                        | -    | -    | 100  | A    |
| Diode Pulse Current                                    | I <sub>s,pulse</sub> |                                                                                       | -    | -    | 400  | A    |
| Diode Forward Voltage                                  | V <sub>SD</sub>      | V <sub>GS</sub> =0V, I <sub>S</sub> =50A                                              | -    | -    | 1.4  | V    |
| Reverse Recovery Time <sup>4</sup>                     | t <sub>rr</sub>      | V <sub>GS</sub> =0V, I <sub>S</sub> =50A, dI <sub>f</sub> /dt=100A/μs,                | -    | 96   | -    | nS   |
| Reverse Recovery Charge <sup>4</sup>                   | Q <sub>rr</sub>      | V <sub>R</sub> =48V                                                                   | -    | 0.35 | -    | nC   |

Notes:

1. EAS test condition:  $L=0.1\text{mH}, V_{DD}=100V, R_G=25\Omega$ .
2. Pulse time of  $5\mu s$ .
3. The dissipated power value will change with the temperature. When it is greater than  $25^{\circ}\text{C}$ , the dissipated power value will decrease by  $1.11^{\circ}\text{C/W}$  for every 1 degree of temperature increase.
4. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$
5. Basically unaffected by operating temperature.

## Typical Electrical and Thermal Characteristic Curves

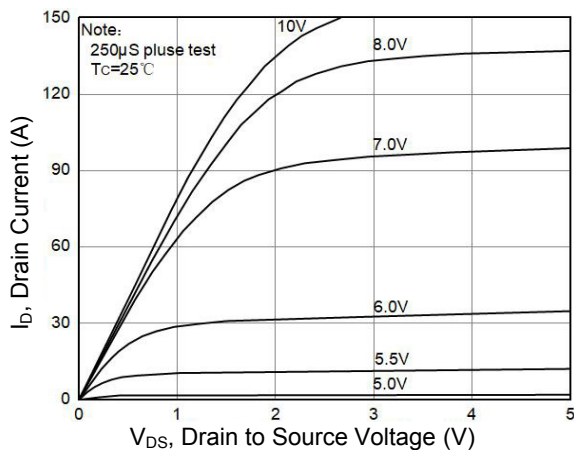


Figure 1. Typical Output Characteristics

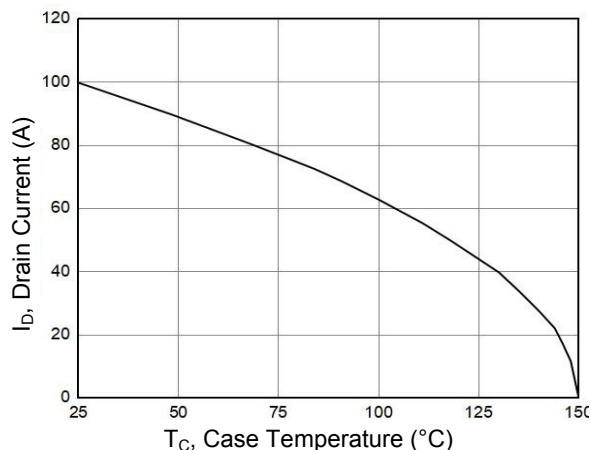


Figure 2. Power Dissipation vs. T<sub>c</sub>

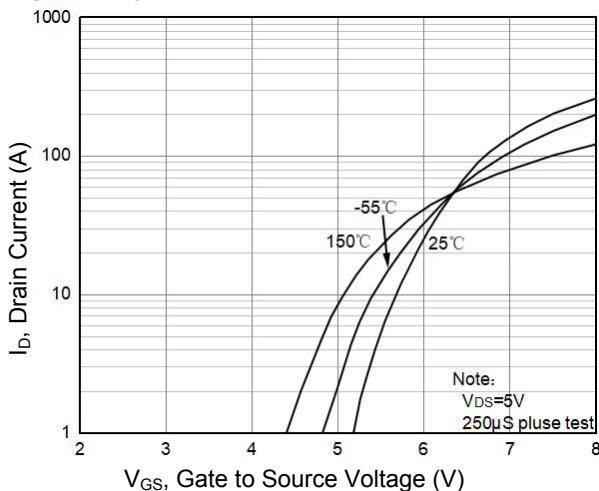


Figure 3. Transfer Characteristics

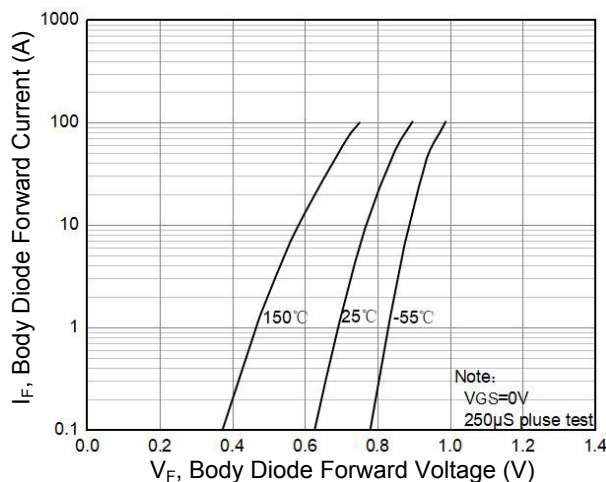


Figure 4. Body Diode Characteristics

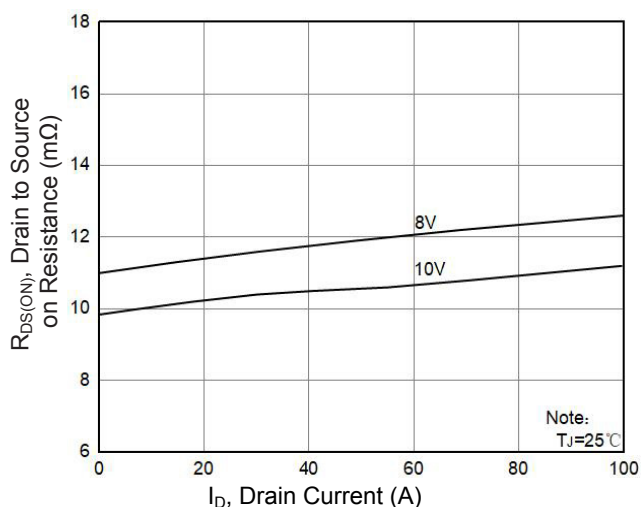


Figure 5. R<sub>DS(ON)</sub> vs. Drain Current

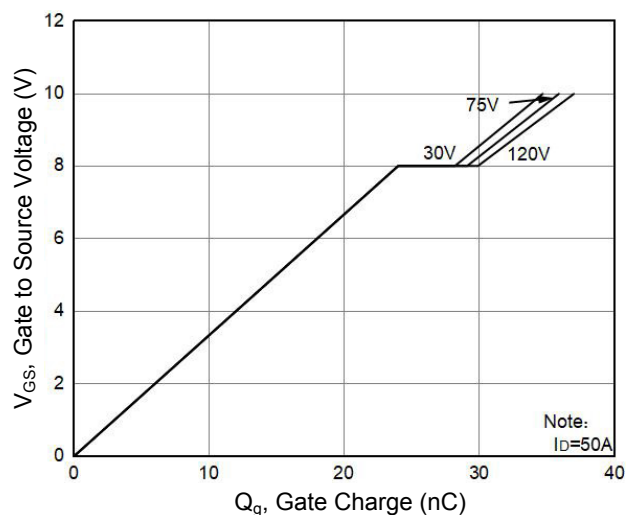
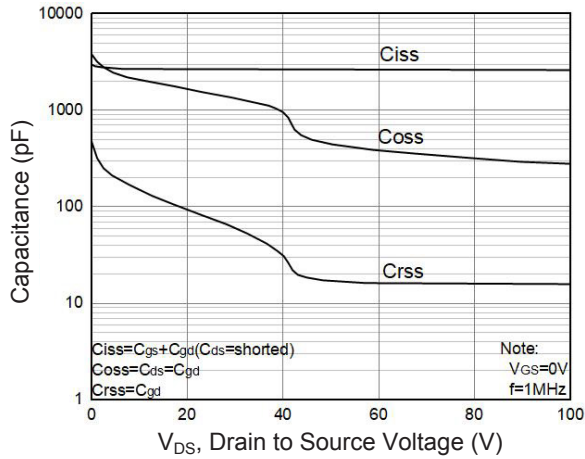
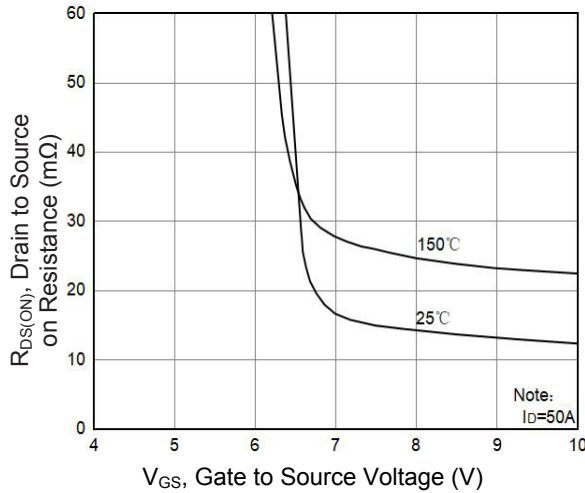


Figure 6. Gate Charge Characteristics

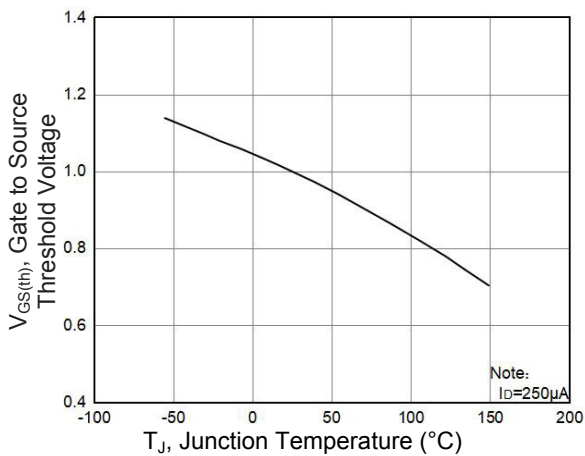
### Typical Electrical and Thermal Characteristic Curves



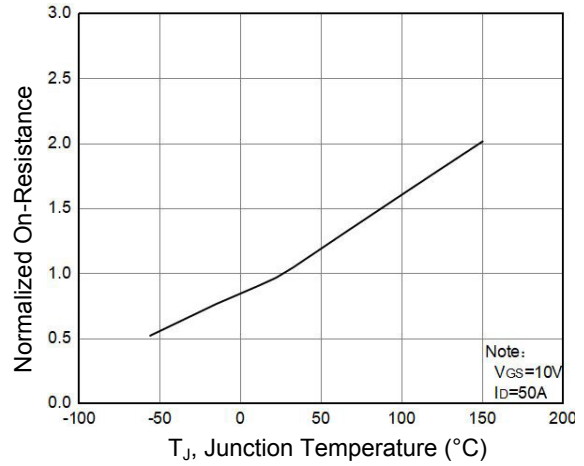
**Figure 7. Capacitance Characteristics**



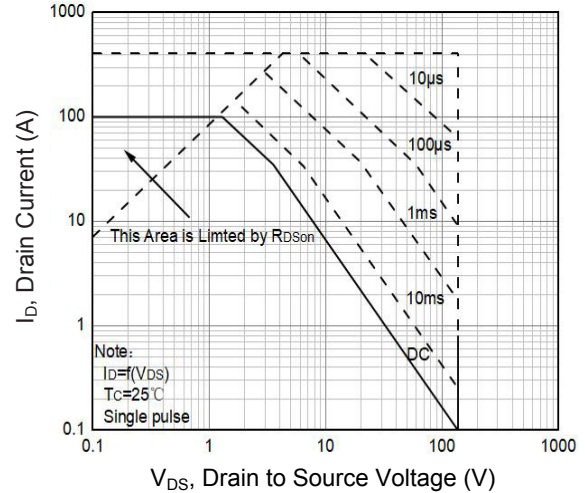
**Figure 9.  $R_{DS(ON)}$  vs.  $V_{GS}$**



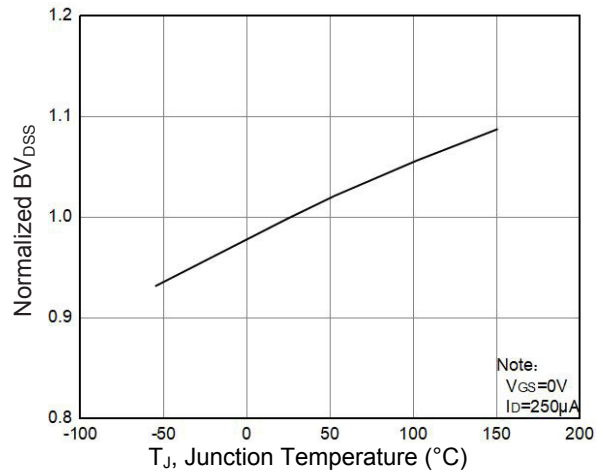
**Figure 11. Gate Threshold Voltage vs  $T_J$**



**Figure 8. Normalized  $R_{DS(ON)}$  vs.  $T_J$**

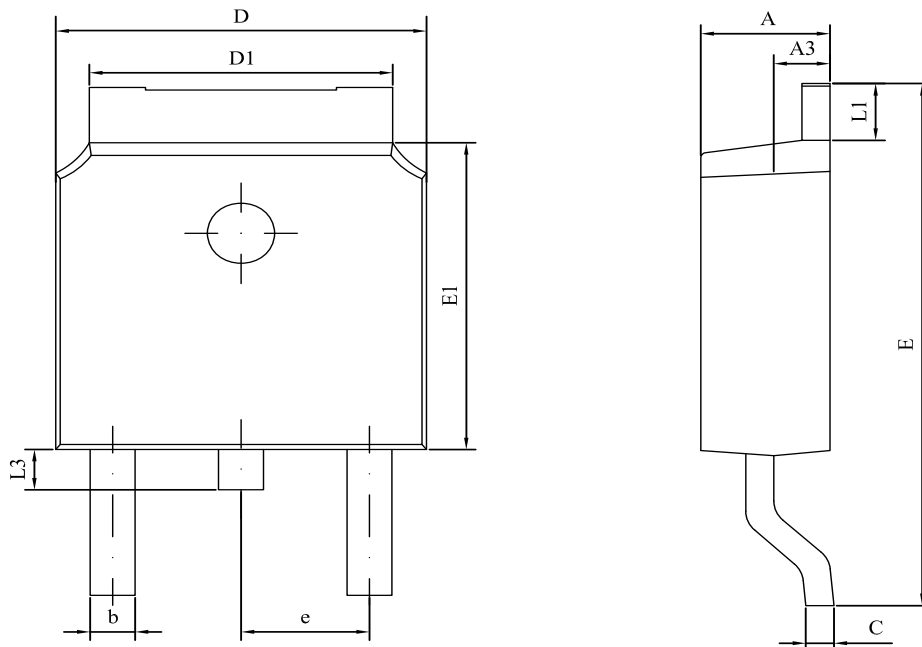


**Figure 10. Safe Operation Area**



**Figure 12. Normalized  $BV_{DSS}$  vs.  $T_J$**

## Package Outline Dimensions TO-252(DPAK)



| Symbol | Dimensions In Millimeters |        | Dimensions In Inches |       |
|--------|---------------------------|--------|----------------------|-------|
|        | Min                       | Max    | Min                  | Max   |
| A      | 2.150                     | 2.400  | 0.085                | 0.094 |
| A3     | 0.900                     | 1.100  | 0.035                | 0.043 |
| b      | 0.500                     | 0.900  | 0.020                | 0.035 |
| C      | 0.400                     | 0.650  | 0.016                | 0.026 |
| D      | 6.300                     | 6.900  | 0.248                | 0.272 |
| D1     | 4.950                     | 5.500  | 0.195                | 0.217 |
| E      | 9.400                     | 10.410 | 0.370                | 0.410 |
| E1     | 5.900                     | 6.300  | 0.232                | 0.248 |
| e      | 2.286 BSC                 |        | 0.090 BSC            |       |
| L1     | 0.890                     | 1.270  | 0.035                | 0.050 |
| L3     | 0.600                     | 1.100  | 0.024                | 0.043 |

## Order Information

| Device    | Package      | Marking | Carrier     | Quantity         |
|-----------|--------------|---------|-------------|------------------|
| GSFD14015 | TO-252(DPAK) | D14015  | Tape & Reel | 2,500 Pcs / Reel |

For more information, please contact us at: [inquiry@goodarksemi.com](mailto:inquiry@goodarksemi.com)